

Title of Change:	SOD-323EP Surface Mount Schottky and Rectifiers Capacity Expansion with Automatic Line				
Proposed first ship date:	29 January 2019				
Contact information:	Contact your local ON Semiconductor Sales Office or <benjo.rulona@onsemi.com></benjo.rulona@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office or < <u>PCN.samples@onsemi.com</u> > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				
Additional Reliability Data:	Contact your	local ON Semiconductor Sales Office of	or <ken.fe< th=""><th>rgus@onsemi.com&gt;</th></ken.fe<>	rgus@onsemi.com>	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < <u>PCN.Support@onsemi.com&gt;</u>				
Change Part Identification:	Cut off datecode: 0419. Current line is also retained in production				
Change Category:	🗌 Wafer Fab	Change Assembly Change	Tes	st Change 🔲 Other	
Change Sub-Category(s):       Manufacturing Site Addition         Manufacturing Site Transfer       Material Change         Manufacturing Process Change       Product specific change			<ul> <li>Datasheet/Product Doc change</li> <li>Shipping/Packaging/Marking</li> <li>Other: Expand capacity with automatic line</li> </ul>		
Sites Affected:	ON Semiconductor Sites: None		External Foundry/Subcon Sites: I-lan, Taiwan		
Description and Purpose:					
		Before Change Description	ì	After Change Description	
Assembly Process		Semi-Automatic Assembly and Mole Processes (Current)	b	Semi-Automatic (Current) and New Fully Automatic Assembly and Mold Process	
There are no product material changes as a result of this change. All are the same. No difference in form, fit and function between products manufactured in both semi-automatic assembly and mold lines and fully automatic assembly and mold lines. This is just capacity expansion to increase productivity and meet customer demands.					



## **Reliability Data Summary:**

## QV DEVICE NAME Lots 1,2,3: NRVBSS14HE, NRVBSS16HE : PACKAGE: <u>SOD-323EP</u>

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1000 hrs	0/231
НЗТНВ	JESD22-A101	TA=85°C+/-2°C RH=85%+/-5% VR=80% rated V DC	1000 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	1000 hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260 °C		0/693
IOL	MIL-STD-750 (M1037) AEC-Q101	I=IF±10% DC supply On time: 2 mins at least , Off time : 2 mins at least	15000 cyc	0/231
тс	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
AC	JESD-A102	TA=121°C, P=15psig Relative Humidity = 100%	96 hrs	0/231
RSH	JESD22- B106	Ta = 260±5°C, 10±1sec; Dipping depth=within 1.27mm of the body		0/90
SD	JSTD002	Ta = 245±5C, 5±0.5 sec		0/30

## QV DEVICE NAME Lots 4,5,6: S1JHE: PACKAGE: <u>SOD-323EP</u>

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1000 hrs	0/231
НЗТНВ	JESD22-A101	TA=85°C+/-2°C RH=85%+/-5% VR=80% rated V DC	1000 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	1000 hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260 °C		0/693
IOL	MIL-STD-750 (M1037) AEC-Q101	I=IF±10% DC supply On time: 2 mins at least , Off time : 2 mins at least	15000 cyc	0/231
тс	JESD22-A104	Ta= -55°C to +150°C	1000 сус	0/231
AC	JESD-A102	TA=121°C, P=15psig Relative Humidity = 100%	96 hrs	0/231
RSH	JESD22- B106	Ta = 260±5°C, 10±1sec; Dipping depth=within 1.27mm of the body		0/90
SD	JSTD002	Ta = 245±5C, 5±0.5 sec		0/30



Electrical Characteristic Summary:	
Electrical characteristics are not impacted.	
List of Affected Parts:	
Part Number	Qualification Vehicle
S1GHE	S1JHE
	611115
S1JHE	S1JHE
S1JHE SS13HE	NRVBSS14HE

## **Appendix A: Changed Products**

Product	Customer Part Number	Qualification Vehicle	
S1GHE		S1JHE	
S1JHE		S1JHE	
SS13HE		NRVBSS14HE	
SS14HE		NRVBSS14HE	
SS16HE		NRVBSS16HE	